

Systronic
att. Mr J Gerault
6, avenue de l' atlantique
Z.A. Courtaboeuf
91955 Les Ulis Cedex
France

Our ref. ESA-TECMSP-LE-2023-001670

.....
Noordwijk, 15/09/2023

VISA: T Rohr (TEC-MSP)

Subject: Qualification renewal of rigid polyimide PCBs from Systronic

Dear Mr Gerault,

Systronic submitted a rigid polyimide PCB to ESA for qualification renewal in March 2023. The results are reported in ESA-TECMSP-TR-2023-001382. The inspected board showed no deviation from the specification.

In addition, Systronic performed a risk analysis for the PID capability update as reported in SY 1069-21 - Risk Analysis on PID Evolution - 20 Rigid layer V5. As a result, the PID has been updated to issue 12 to cover the 20-layer build-up. A close-out meeting held on 8 July 2022 concluded the successful outcome of the PID capability update.

Systronic is considered qualified in accordance with ECSS-Q-ST-70-60C for the manufacture of Printed Circuit Boards as follows:

- Rigid sequential polyimide PCBs as per PID 6 v12 until 1 Oct 2025

Best regards,

Jussi Hokka
Materials & Processes Section